# PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Joseph Andrew MARTIN	05/24/2006
King Yin Fred FU	05/24/2006
Hoi Ping Patrick PHEN	05/24/2006

### **RECEIVING PARTY DATA**

Name:	QPL Limited	
Street Address:	Unit F, 17/F, CDW Building, 388 Castle Peak Road, Tsuen Wan, NT	
City:	Hong Kong	
State/Country:	CHINA	

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11399542

## **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: Q001.001US

NAME OF SUBMITTER: Jacqueline C. Lui

Total Attachments: 4

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PATENT REEL: 017873 FRAME: 0339

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PATENT REEL: 017873 FRAME: 0340

#### ASSIGNMENT

WHEREAS, We, Joseph Andrew MARTIN, a USA citizen, residing at Unit F, 17/F, CDW Building, 388 Castle Peak Road, Tsuen Wan, NT, Hong Kong; King Yin Fred FU, a Hong Kong citizen, residing at Unit F, 17/F, CDW Building, 388 Castle Peak Road, Tsuen Wan, NT, Hong Kong; Hoi Ping Patrick PHEN, a Hong Kong citizen, residing at Unit F, 17/F CDW Building, 388 Castle Peak Road, Tsuen Wan, NT, Hong Kong (hereinafter "INVENTORS") have invented certain new and useful improvements in a ELECTRONIC DEVICE WITH SELECTIVE NICKEL PALLADIUM GOLD PLATED LEADFRAME AND METHOD OF MAKING THE SAME for which an application for a United States Patent was filed on 7 April 2006 under application number 11/399,542;

AND WHEREAS, QPL Limited (hereinafter "ASSIGNEE"), a Hong Kong Corporation, with its registered place of business at Unit F, 17/F, CDW Building, 388 Castle Peak Road, Tsuen Wan, NT, Hong Kong desires to acquire the entire right, title, and interest in and to the said Invention and the said Application:

NOW, THEREFORE, in consideration of One Dollar (USD 1.00) to INVENTORS, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said Inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said Application and all applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE DO HEREBY sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

SIGNED this 24 day of May 2006.

RECORDED: 07/04/2006

Joseph Andrew MARTIN

King Yin Fred FU

Hoi Ping Patrick PHEN

PATENT REEL: 017873 FRAME: 0341